



#### 12V P-CHANNEL ENHANCEMENT MODE MOSFET

#### **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	I <sub>D</sub> Max T <sub>A</sub> = +25°C
	$15m\Omega @ V_{GS} = -4.5V$	-8.5A
-12V	$20m\Omega$ @ $V_{GS} = -3.7V$	-7.3A
	$25m\Omega$ @ $V_{GS} = -3.3V$	-6.6A
	$30 \text{m}\Omega$ @ $V_{GS} = -2.5 \text{V}$	-6.0A
	40mΩ @ V <sub>GS</sub> = -1.8V	-5.2A

### **Description and Applications**

This MOSFET is designed to minimize the on-state resistance  $(R_{DS(ON)})$  and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Motor Control
- Backlighting
- Power Management Functions
- DC-DC Converters

## **Features and Benefits**

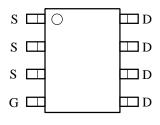
- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

#### **Mechanical Data**

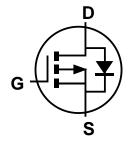
- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminal Connections Indicator: See Diagram Below
- Terminals: Finish Matte Tin Annealed over Copper Lead Frame. Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.074 grams (Approximate)







Top View Internal Schematic



**Equivalent Circuit** 

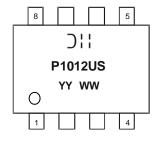
#### **Ordering Information** (Note 4)

Part Number	Case	Packaging
DMP1012USS-13	SO-8	2,500/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

# **Marking Information**



);; = Manufacturer's Marking
P1012US = Product Type Marking Code
YYWW = Date Code Marking
YY or YY = Year (ex: 18 = 2018)
WW = Week (01 to 53)



### **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	V <sub>DSS</sub>	-12	V		
Gate-Source Voltage	$V_{GSS}$	±8	V		
Continuous Drain Current (Note 6) $V_{GS} = -4.5V$ Steady $T_A = +25^{\circ}C$ State $T_A = +70^{\circ}C$			I <sub>D</sub>	-8.5 -6.8	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I <sub>DM</sub>	-40	Α		
Maximum Continuous Body Diode Forward Current (Note 6)			Is	-2	Α
Pulsed Body Diode Forward Current (10μs Pulse, Duty Cycle = 1%)			I <sub>SM</sub>	-40	Α
Avalanche Current (Note 7) L = 0.1mH			I <sub>AS</sub>	-21	Α
Avalanche Energy (Note 7) L = 0.1mH			E <sub>AS</sub>	22	mJ

### Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Total Power Dissipation (Note 5)	Steady State	$T_A = +25^{\circ}C$	$P_{D}$	1.3	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady state	$R_{ heta JA}$	99	°C/W	
Total Power Dissipation (Note 6) Steady State		$T_A = +25^{\circ}C$	P <sub>D</sub>	1.6	W
Thermal Resistance, Junction to Ambient (Note 6)  Steady			$R_{ heta JA}$	77	°C/W
Thermal Resistance, Junction to Case (Note 6)			$R_{ heta JC}$	13	C/VV
Operating and Storage Temperature Range			$T_{J_i} T_{STG}$	-55 to +150	°C

# Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

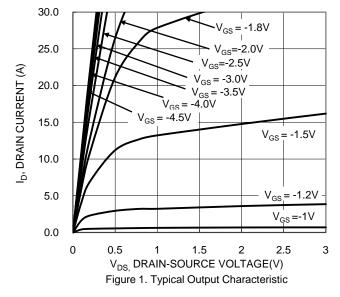
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-12	I	_	V	$V_{GS} = 0V, I_D = -250\mu A$	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_		-1	μΑ	$V_{DS} = -9.6V, V_{GS} = 0V$	
Gate-Source Leakage	$I_{GSS}$	_		±100	nA	$V_{GS} = \pm 8V$ , $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	-0.4	-	-1.0	V	$V_{DS} = V_{GS}$ , $I_D = -250\mu A$	
			9	15	mΩ	$V_{GS} = -4.5V, I_{D} = -9A$	
			10	20		$V_{GS} = -3.7V, I_D = -7A$	
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>		11	25		$V_{GS} = -3.3V$ , $I_{D} = -7A$	
			13	30		$V_{GS} = -2.5V, I_{D} = -6A$	
			18	40		$V_{GS} = -1.8V, I_{D} = -4A$	
Diode Forward Voltage	$V_{SD}$	_	-0.8	-1.2	٧	$V_{GS} = 0V, I_{S} = -1A$	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	C <sub>iss</sub>	_	1344			101/ 1/ 01/	
Output Capacitance	Coss	_	342	_	pF	VDS = -10V, VGS = 0V, f = 1.0MHz	
Reverse Transfer Capacitance	C <sub>rss</sub>	_	297	_			
Gate Resistance	$R_{g}$	_	15	l	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Total Gate Charge (V <sub>GS</sub> = -4.5V)	$Q_g$	_	19.5	_		V <sub>DS</sub> = -6V, I <sub>D</sub> = -10A	
Total Gate Charge (V <sub>GS</sub> = -8V)	$Q_g$	_	31	_	nC		
Gate-Source Charge	$Q_{gs}$	_	2.1	-	IIC		
Gate-Drain Charge	$Q_{gd}$		7.9	_			
Turn-On Delay Time	t <sub>D(ON)</sub>		6.0	_			
Turn-On Rise Time	t <sub>R</sub>	_	32	_	ns	$V_{DS} = -6V, V_{GS} = -4.5V,$ $R_g = 1\Omega, I_D = -8A$	
Turn-Off Delay Time	t <sub>D(OFF)</sub>	_	71	_	TIS		
Turn-Off Fall Time	t <sub>F</sub>	_	85	_			
Reverse Recovery Time	t <sub>RR</sub>	_	46	_	ns	1 424 4:/44 5004/:	
Reverse Recovery Charge	Q <sub>RR</sub>	_	44	_	nC	I <sub>F</sub> = -12A, di/dt = 500A/μs	

5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
- Bevice involved on the state of board, 202 copper, with find square copper.
   I<sub>AS</sub> and E<sub>AS</sub> ratings are based on low frequency and duty cycles to keep T<sub>J</sub> = +25°C.
   Short duration pulse test used to minimize self-heating effect.
   Guaranteed by design. Not subject to product testing.

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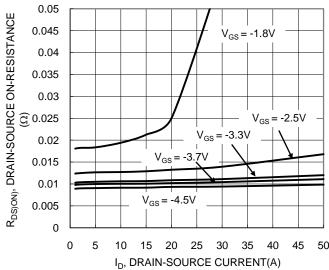


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

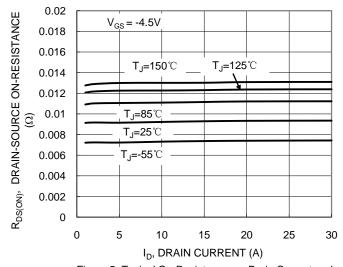
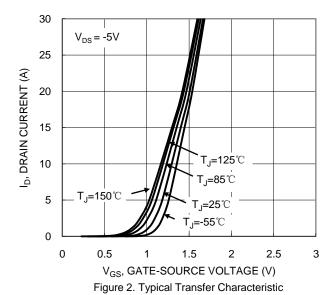


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature



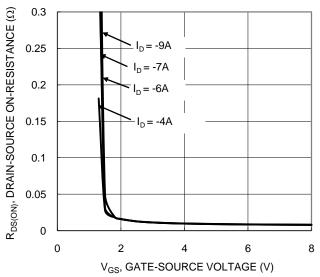


Figure 4. Typical Transfer Characteristic

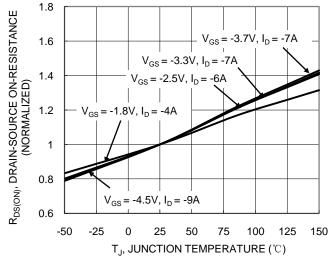


Figure 6. On-Resistance Variation with Junction Temperature



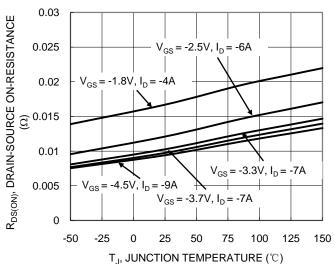
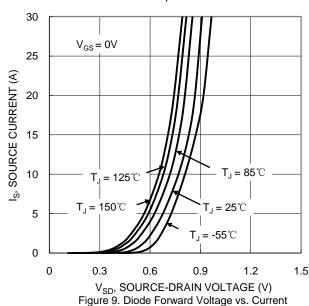


Figure 7. On-Resistance Variation with Junction Temperature



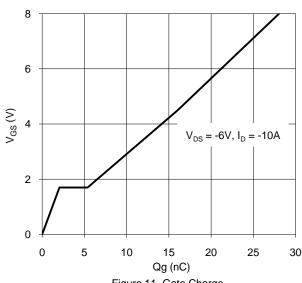


Figure 11. Gate Charge

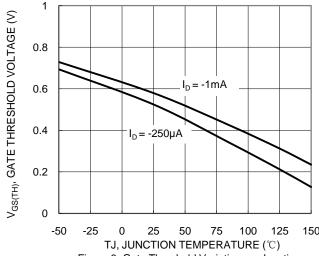
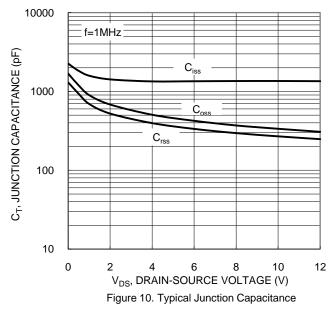
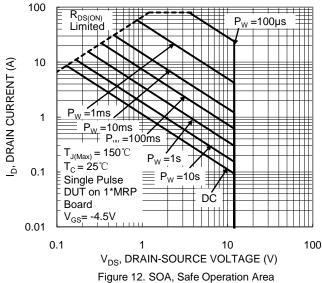


Figure 8. Gate Threshold Variation vs. Junction Temperature







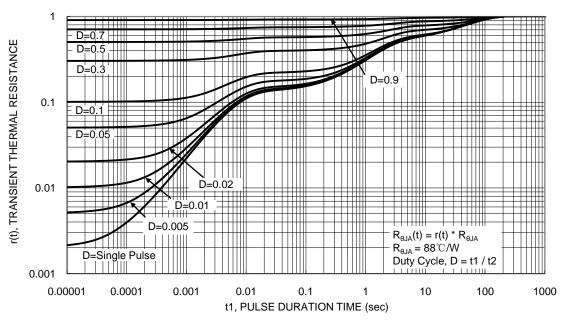
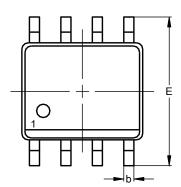


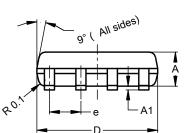
Figure 13. Transient Thermal Resistance

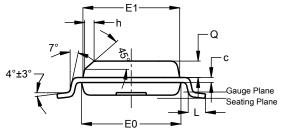


## **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.





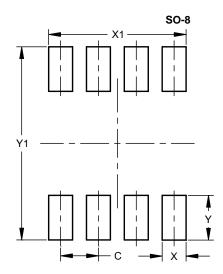


**SO-8** 

SO-8						
Dim	Min	Max	Тур			
Α	1.40	1.50	1.45			
A1	0.10	0.20	0.15			
b	0.30	0.50	0.40			
С	0.15	0.25	0.20			
D	4.85	4.95	4.90			
Е	5.90	6.10	6.00			
E1	3.80	3.90	3.85			
E0	3.85	3.95	3.90			
e 1.2		1.27				
h	ı		0.35			
L	0.62	0.82	0.72			
Q	0.60	0.70	0.65			
All Dimensions in mm						

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)			
С	1.27			
Х	0.802			
X1	4.612			
Y	1.505			
Y1	6.50			

August 2018



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